

01-02-2001


 Key Docket No. 16869P-010500US  
 Client Ref. No. 3499005287US1

 FORM PTO-1595  
 (Rev. 6-93)

 101569054  
 (Patents Only)

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To the Honorable Asst. Commissioner for Patents. Please record the attached original documents or copy thereof

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3. Nature of conveyance:  <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other:  Execution Dates: July 27, 2000	
4. Application Number(s) or Patent Numbers.  If this document is being filed together with a new application, the execution date of the application is:  A. Patent Application No(s): 09/631,889 B. Patent No(s):  Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
5. Name and address of party to whom correspondence concerning document should be mailed:  Name: Paul A. Durdik TOWNSEND AND TOWNSEND AND CREW LLP Two Embarcadero Center, 8 <sup>th</sup> Floor San Francisco, California 94111-3834 (650) 326-2400	6. Total number of applications and patents involved 1  7. Total fee (37 CFR 3.41): \$40.00 <input type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Charge Fees to Deposit Account  <input checked="" type="checkbox"/> Charge any additional fees associated with this paper or during the pendency of this application, or credit any overpayment, to deposit account.  8. Deposit account number: 20-1430

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9. Statement and signature.  <i>To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true of copy of the original document.</i>  <div style="display: flex; justify-content: space-between;"> <div>           Paul A. Durdik            Name of Person Signing             Atty Reg. No. <u>37,819</u> </div> <div style="text-align: center;">             Signature         </div> <div>           December 4, 2000            Date             Total number of pages including cover sheet, attachments and document - <u>2</u> </div> </div>		
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 PATENT  
 REEL: 11374 FRAME: 0973

# ASSIGNMENT

( 譲渡証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## Device for sealing and cooling multi-chip modules

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1)	<u>Takahiro Daikoku</u>	<u>July 27, 2000</u>
2)	<u>Kenichi Kasai</u>	<u>July 27, 2000</u>
3)	<u>Toshitada Netsu</u>	<u>July 27, 2000</u>
4)	<u>Koichi Koyano</u>	<u>July 27, 2000</u>
5)	<u>Takayaki Uda</u>	<u>July 27, 2000</u>
6)	<u>                                </u>	<u>                                </u>
7)	<u>                                </u>	<u>                                </u>
8)	<u>                                </u>	<u>                                </u>